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	LEAD-FREE PF	RODUCTS (see r	ote 9)									
	DESCRIPTION		PRODUCT NUMBER	CONTACT AREA PLATING**	MAXIMUM EXTERNAL Ø CABLE	SOLDER AREA PLATING	AWG*					
A	KIT		53389-001LF									
		CONSIST OF:										
	COVER UPPER	53230-001LF	1	6 micron Sn over Cu & Ni		N A						
	COVER LOWER	53231-001LF	I	6 micron Sn over Cu & Ni		N A						
	WAFER	53238-001LFLF	2	2 micron Au over Ni		2.5-7.5µm Sn over 1.27µm Ni mir	24 to 26					
	FERRULE OUTER	53236-001LF	1	6 micron Sn over Ni		N A						
	FERRULE INNER	53235-001LF	I	6 micron Sn over Ni	5.30	N A						
	SCREW	72780-001LF	2			N A						
	SHROUD	85710-001LF	I			N A						
	**Please o	consult FCI	for alterno	ite plating thick	(nesses							
>												
)							Dr PE Eng PE Chr LE	ERRICHOT 2003/10/27 ERRICHOT 2003/10/27 EGARE 2003/10/27 0° ±2° EGARE 2003/10/27 Product SOFIX SHIELDED I BEAMON GIGABIT LINK	ISO 406 UNLESS OTHERWISE S O.X O.XX O.XXX family	#0.3 size #3 #40.1 A3 #40.05 ECN #50FIX Spec ref	Scale 1:1 LS06-0143 SEE NOTES Rev	
	REV F - 2006-04-17								53389-001x	CUSTOMER	sheet 3 of 3	
					2			3	DM: Rev:F	s∱atus Released	Printed: Apr 17, 2008	